



# SURFACE MOUNT GLASS PASSIVATED RECTIFIER S3A~ S3M

## Surface Mount Glass Passivated Rectifier

### Features

- Glass passivated chip junction
- Built in strain relief
- High current capability
- Low forward voltage drop
- Fast switching speed for high efficiency
- High temperature Soldering guaranteed: 260°C / 10 seconds at terminals
- RoHS and REACH compliance



RoHS  
COMPLIANT

DO-214AB (SMC)

### Mechanical Data

<b>Case:</b>	JEDEC DO-214AB(SMC), transfer molded plastic
<b>Epoxy:</b>	Meets UL 94V-0 flammability rating
<b>Terminals:</b>	Solder plated, solderable per MIL-STD 750, Method 2026
<b>Polarity:</b>	Cathode indicated by color band
<b>Mounting position:</b>	Any
<b>Weight:</b>	0.007 ounce, 0.25 gram

### Maximum Ratings ( $T_{Ambient}=25^{\circ}C$ unless noted otherwise)

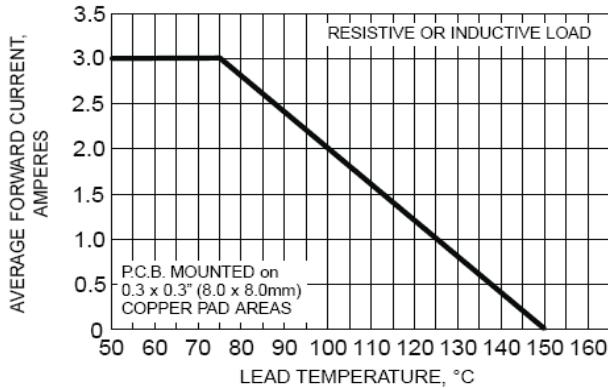
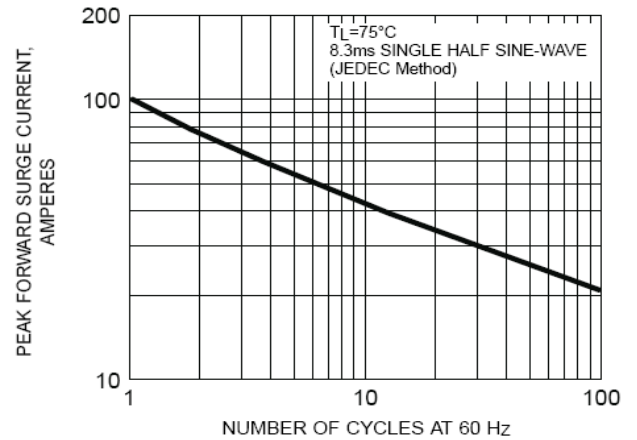
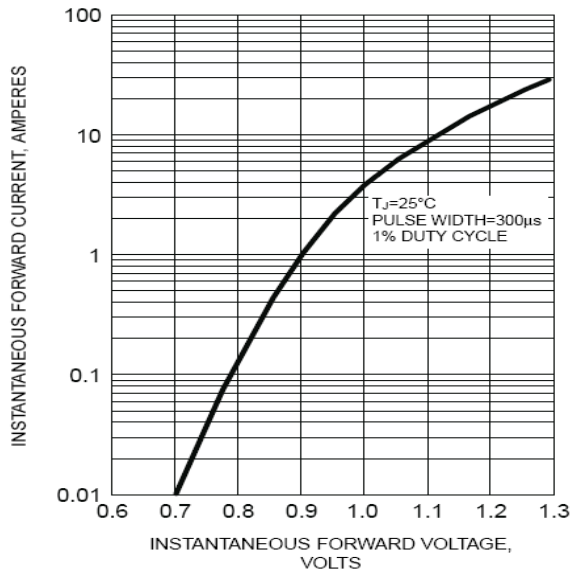
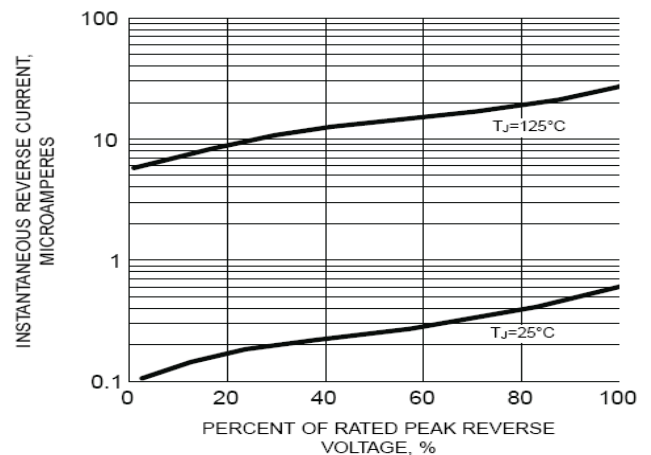
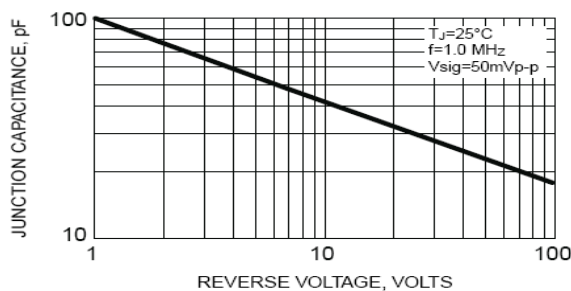
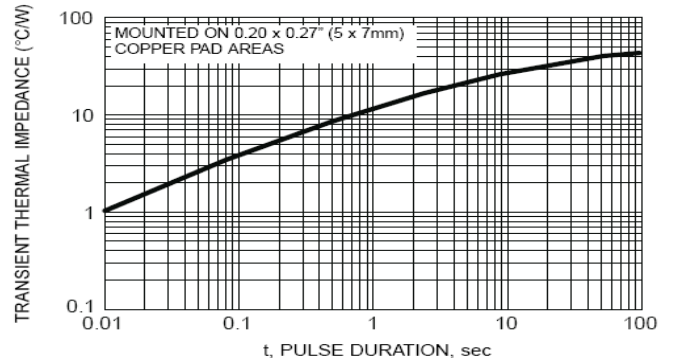
Symbol	Description	S3A	S3B	S3D	S3G	S3J	S3K	S3M	Unit	Conditions
VRRM	Max Recurrent Peak Reverse Voltage	50	100	200	400	600	800	1000	V	
VRMS	Max RMS Voltage	35	70	140	280	420	560	700	V	
VDC	Max DC Blocking Voltage	50	100	200	400	600	800	1000	V	
I(AV)	Max Average Forward Rectified Current at Ambient Temperature	3.0							A	TL=75°C (note 2)
IFSM	Peak Forward Surge Current	100							A	8.3ms single half sine-wave (JEDEC)
trr	Maximum Reverse Recovery Time	2.5							μS	IF=0.5A, IR=1.0A, IRR=0.25A
TJ,TSTG	Operating and Storage Temperature Range	-55 to +150							°C	

### Electrical Characteristics ( $T_{Ambient}=25^{\circ}C$ unless noted otherwise)

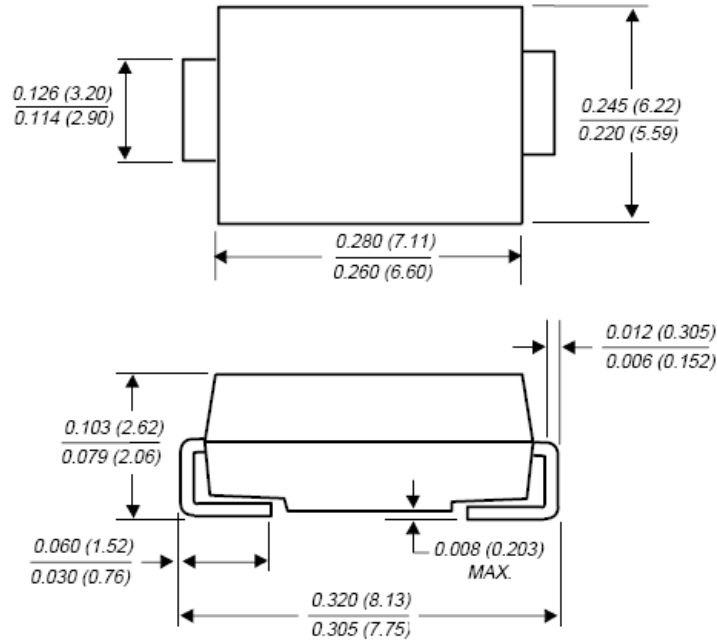
Symbol	Description	S3A	S3B	S3D	S3G	S3J	S3K	S3M	Unit	Conditions
VF	Max Instantaneous Forward Voltage	1.2							V	IF(AV)= 3.0A
IR	Max DC Reverse Current at Rated DC Blocking Voltage	5.0							μA	TA=25°C
		250								TA=125°C
CJ	Typical Junction Capacitance	60							pF	At 1MHz, reversed voltage of 4V
Rθ-JA	Typical Thermal Resistance	47							°C/W	Note 2
Rθ-JL		13								

#### Note:

1. Single phase, half wave, 60Hz, resistive or inductive load. Derate current by 20% for capacitive load
2. Thermal Resistance from junction to ambient and from junction to lead mounted on PCB with 0.3" x 0.3" (8.0mm x 8.0mm) copper pad areas.

**Typical Characteristics Curves**
**FIG. 1 - FORWARD CURRENT DERATING CURVE**

**FIG. 2 - MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT**

**FIG. 3 - TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS**

**FIG. 4 - TYPICAL REVERSE CHARACTERISTICS**

**FIG. 5 - TYPICAL JUNCTION CAPACITANCE**

**FIG. 6 - TYPICAL TRANSIENT THERMAL IMPEDANCE**


Dimensions in inch (mm)

**DO-214AB(SMC)****Contact us:****US HEADQUARTERS****MEI SEMI INC.****2902** Corvin Drive, Santa Clara, CA95051, USA

Tel: 1-408-733-0808 Fax: 1-408-733-2828